

| L Number | Hits | Search Text | DB | Time stamp |
|-------------|------|--|----------------------------------|---------------------|
| 1 | 879 | (chip same substrate) and resin and (die same pressure) | USPAT; US-PGPUB | 2004/09/29 17:32 |
| 2 | 54 | (chip same substrate) and ((melted or melting) near3 resin) and (die same pressure) | USPAT; US-PGPUB | 2004/09/29 16:46 |
| 3 | 47 | ((chip same substrate) and ((melted or melting) near3 resin) and (die same pressure)) and @ad<20020927 | USPAT; US-PGPUB | 2004/09/29 16:46 |
| 4 | 25 | (chip same substrate) and resin and (die same pressure) | EPO; JPO; DERWENT; IBM TDB | 2004/09/29 17:33 |